

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT3059746

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
DEBESH KUMAR SAHU	10/09/2014
GEORGE CHERIAN	09/29/2014
VENKATA SIVA PRASAD RAO GUDE	09/17/2014
NEELAKANTA VENKATA SESHACHALAM CHIMMAPUDI	09/10/2014
SACHIN JAIN	09/16/2014
RECEIVING PARTY DATA	
Name:	QUALCOMM Incorporated
Street Address:	5775 Morehouse Drive
City:	San Diego
State/Country:	CALIFORNIA
Postal Code:	92121-1714
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	13772761
CORRESPONDENCE DATA	
Fax Number:	(858)658-2502
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	(858) 651-5205
Email:	us-docketing@qualcomm.com
Correspondent Name:	QUALCOMM INCORPORATED
Address Line 1:	5775 MOREHOUSE DRIVE
Address Line 4:	SAN DIEGO, CALIFORNIA 92121-1714
ATTORNEY DOCKET NUMBER:	121184
NAME OF SUBMITTER:	MICHELLE SANFILIPPO
SIGNATURE:	/Michelle Sanfilippo/
DATE SIGNED:	10/09/2014
Total Attachments: 15	
source=121184_UpdatedAssignment_Signed#page1.tif	
source=121184_UpdatedAssignment_Signed#page2.tif	

PATENT

source=121184_UpdatedAssignment_Signed#page3.tif
source=121184_UpdatedAssignment_Signed#page4.tif
source=121184_UpdatedAssignment_Signed#page5.tif
source=121184_UpdatedAssignment_Signed#page6.tif
source=121184_UpdatedAssignment_Signed#page7.tif
source=121184_UpdatedAssignment_Signed#page8.tif
source=121184_UpdatedAssignment_Signed#page9.tif
source=121184_UpdatedAssignment_Signed#page10.tif
source=121184_UpdatedAssignment_Signed#page11.tif
source=121184_UpdatedAssignment_Signed#page12.tif
source=121184_UpdatedAssignment_Signed#page13.tif
source=121184_UpdatedAssignment_Signed#page14.tif
source=121184_UpdatedAssignment_Signed#page15.tif

ASSIGNMENT

WHEREAS, WE,

1. **Debesh Kumar SAHU**, a citizen of India, having a mailing address located at 5775 Morehouse Drive, San Diego, California 92121 and a resident of Hyderabad, Andhra Pradesh, India,
2. **George CHERIAN**, a citizen of India, having a mailing address located at 5775 Morehouse Drive, San Diego, California 92121 and a resident of San Diego, California,
3. **Venkata Siva Prasad Rao GUDE**, a citizen of India, having a mailing address located at 5775 Morehouse Drive, San Diego California 92121 and a resident of San Diego, California,
4. **Neelakanta Venkata Seshachalam CHIMMAPUDI**, a citizen of India, having a mailing address located at 5775 Morehouse Drive, San Diego, California 92121 and a resident of San Diego, California,
5. **Sachin JAIN**, a citizen of India, having a mailing address located at 5775 Morehouse Drive, San Diego, California 92121 and a resident of Sunnyvale, California,

have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to **HIGH-SPEED DATA CHANNEL AVAILABILITY** (collectively the "INVENTIONS") for which WE have executed and/or may execute one or more patent applications therefor; and

WHEREAS, QUALCOMM Incorporated (hereinafter "**ASSIGNEE**"), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to said INVENTIONS, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, WE do hereby acknowledge that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, the entire right, title, and interest throughout the world in and to said INVENTIONS, including all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in the United States, including but not limited to U.S. Application No(s). 13/772,761 filed **February 21, 2013**, Qualcomm Reference No. **121184**, and all provisional applications relating thereto, together with U.S. Provisional Application No(s). **61/618,498**, filed **March 30, 2012**, Qualcomm Reference No. **121184P1**, (and do hereby authorize ASSIGNEE and its representative to hereafter add herein such application number(s) and/or filing date(s) when known), and all divisional applications, renewal applications, continuation applications, continuation-in-part

applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

AND WE further do acknowledge and agree that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;

AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND WE HEREBY represent that WE have full and exclusive, unencumbered right to sell, assign, convey and transfer all subject matter herein, and hereby covenant that WE have not and will not execute any writing or do any act whatsoever conflicting with these presents.

Done at Hyd India, on 10/02/2014 Debash K Sahu
LOCATION DATE Debesh Kumar SAHU

Done at _____, on _____
LOCATION DATE George CHERIAN

Done at _____, on _____
LOCATION DATE Venkata Siva Prasad Rao GUDE

Done at _____, on _____
LOCATION DATE Neelakanta Venkata Seshachalam CHIMMAPUDI

Done at _____, on _____
LOCATION DATE Sachin JAIN

ASSIGNMENT

WHEREAS, WE,

1. **Debesh Kumar SAHU**, a citizen of India, having a mailing address located at 5775 Morehouse Drive, San Diego, California 92121 and a resident of Hyderabad, Andhra Pradesh, India,
2. **George CHERIAN**, a citizen of India, having a mailing address located at 5775 Morehouse Drive, San Diego, California 92121 and a resident of San Diego, California,
3. **Venkata Siva Prasad Rao GUDE**, a citizen of India, having a mailing address located at 5775 Morehouse Drive, San Diego California 92121 and a resident of San Diego, California,
4. **Neelakanta Venkata Seshachalam CHIMMAPUDI**, a citizen of India, having a mailing address located at 5775 Morehouse Drive, San Diego, California 92121 and a resident of San Diego, California,
5. **Sachin JAIN**, a citizen of India, having a mailing address located at 5775 Morehouse Drive, San Diego, California 92121 and a resident of Sunnyvale, California,

have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to **HIGH-SPEED DATA CHANNEL AVAILABILITY** (collectively the "INVENTIONS") for which WE have executed and/or may execute one or more patent applications therefor; and

WHEREAS, QUALCOMM Incorporated (hereinafter "ASSIGNEE"), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to said INVENTIONS, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, WE do hereby acknowledge that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, the entire right, title, and interest throughout the world in and to said INVENTIONS, including all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in the United States, including but not limited to U.S. Application No(s). **13/772,761** filed **February 21, 2013**, Qualcomm Reference No. **121184**, and all provisional applications relating thereto, together with U.S. Provisional Application No(s). **61/618,498**, filed **March 30, 2012**, Qualcomm Reference No. **121184P1**, (and do hereby authorize ASSIGNEE and its representative to hereafter add herein such application number(s) and/or filing date(s) when known), and all divisional applications, renewal applications, continuation applications, continuation-in-part

applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

AND WE further do acknowledge and agree that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;

AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND WE HEREBY represent that WE have full and exclusive, unencumbered right to sell, assign, convey and transfer all subject matter herein, and hereby covenant that WE have not and will not execute any writing or do any act whatsoever conflicting with these presents.

PATENT

QUALCOMM Ref. No. 121184

Page 3 of 3

Done at _____, on _____
LOCATION DATE

Debesh Kumar SAHU

Done at San Diego, on 9/29/2014
LOCATION DATE


George CHERIAN

Done at _____, on _____
LOCATION DATE

Venkata Siva Prasad Rao GUDE

Done at _____, on _____
LOCATION DATE

Neelakanta Venkata Seshachalam CHIMMAPUDI

Done at _____, on _____
LOCATION DATE

Sachin JAIN

PATENT

REEL: 033924 FRAME: 0469

ASSIGNMENT

WHEREAS, WE,

1. **Debesh Kumar SAHU**, a citizen of India, having a mailing address located at 5775 Morehouse Drive, San Diego, California 92121 and a resident of Hyderabad, Andhra Pradesh, India,
2. **George CHERIAN**, a citizen of India, having a mailing address located at 5775 Morehouse Drive, San Diego, California 92121 and a resident of San Diego, California,
3. **Venkata Siva Prasad Rao GUDE**, a citizen of India, having a mailing address located at 5775 Morehouse Drive, San Diego California 92121 and a resident of San Diego, California,
4. **Neelakanta Venkata Seshachalam CHIMMAPUDI**, a citizen of India, having a mailing address located at 5775 Morehouse Drive, San Diego, California 92121 and a resident of San Diego, California,
5. **Sachin JAIN**, a citizen of India, having a mailing address located at 5775 Morehouse Drive, San Diego, California 92121 and a resident of Sunnyvale, California,

have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to **HIGH-SPEED DATA CHANNEL AVAILABILITY** (collectively the "INVENTIONS") for which WE have executed and/or may execute one or more patent applications therefor; and

WHEREAS, QUALCOMM Incorporated (hereinafter "ASSIGNEE"), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to said INVENTIONS, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, WE do hereby acknowledge that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, the entire right, title, and interest throughout the world in and to said INVENTIONS, including all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in the United States, including but not limited to U.S. Application No(s). **13/772,761** filed **February 21, 2013**, Qualcomm Reference No. **121184**, and all provisional applications relating thereto, together with U.S. Provisional Application No(s). **61/618,498**, filed **March 30, 2012**, Qualcomm Reference No. **121184P1**, (and do hereby authorize ASSIGNEE and its representative to hereafter add herein such application number(s) and/or filing date(s) when known), and all divisional applications, renewal applications, continuation applications, continuation-in-part

applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

AND WE further do acknowledge and agree that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;

AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND WE HEREBY represent that WE have full and exclusive, unencumbered right to sell, assign, convey and transfer all subject matter herein, and hereby covenant that WE have not and will not execute any writing or do any act whatsoever conflicting with these presents.

PATENT

QUALCOMM Ref. No. 121184

Page 3 of 3

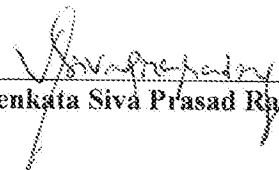
Done at _____, on _____
LOCATION DATE

Debesh Kumar SAHU

Done at _____, on _____
LOCATION DATE

George CHERIAN

Done at SAN, PILEG, CA, on 9/17/14
LOCATION DATE


Venkata Siva Prasad Rao GUDE

Done at _____, on _____
LOCATION DATE

Neelakanta Venkata Seshachalam CHIMMAPUDI

Done at _____, on _____
LOCATION DATE

Sachin JAIN

PATENT

REEL: 033924 FRAME: 0472

ASSIGNMENT

WHEREAS, WE,

1. **Debesh Kumar SAHU**, a citizen of India, having a mailing address located at 5775 Morehouse Drive, San Diego, California 92121 and a resident of Hyderabad, Andhra Pradesh, India,
2. **George CHERIAN**, a citizen of India, having a mailing address located at 5775 Morehouse Drive, San Diego, California 92121 and a resident of San Diego, California,
3. **Venkata Siva Prasad Rao GUDE**, a citizen of India, having a mailing address located at 5775 Morehouse Drive, San Diego California 92121 and a resident of San Diego, California,
4. **Neelakanta Venkata Seshachalam CHIMMAPUDI**, a citizen of India, having a mailing address located at 5775 Morehouse Drive, San Diego, California 92121 and a resident of San Diego, California,
5. **Sachin JAIN**, a citizen of India, having a mailing address located at 5775 Morehouse Drive, San Diego, California 92121 and a resident of Sunnyvale, California,

have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to **HIGH-SPEED DATA CHANNEL AVAILABILITY** (collectively the "INVENTIONS") for which WE have executed and/or may execute one or more patent applications therefor; and

WHEREAS, QUALCOMM Incorporated (hereinafter "ASSIGNEE"), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to said INVENTIONS, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, WE do hereby acknowledge that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, the entire right, title, and interest throughout the world in and to said INVENTIONS, including all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in the United States, including but not limited to U.S. Application No(s). **13/772,761** filed **February 21, 2013**, Qualcomm Reference No. **121184**, and all provisional applications relating thereto, together with U.S. Provisional Application No(s). **61/618,498**, filed **March 30, 2012**, Qualcomm Reference No. **121184P1**, (and do hereby authorize ASSIGNEE and its representative to hereafter add herein such application number(s) and/or filing date(s) when known), and all divisional applications, renewal applications, continuation applications, continuation-in-part

applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

AND WE further do acknowledge and agree that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;


AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND WE HEREBY represent that WE have full and exclusive, unencumbered right to sell, assign, convey and transfer all subject matter herein, and hereby covenant that WE have not and will not execute any writing or do any act whatsoever conflicting with these presents.

Done at _____, on _____
LOCATION DATE Debesh Kumar SAHU

Done at _____, on _____
LOCATION DATE George CHERIAN

Done at _____, on _____
LOCATION DATE Venkata Siva Prasad Rao GUDE

Done at Saundharabad, on 5/8/10/2004
LOCATION DATE  Neelakanta Venkata Seshachalam CHIMMAPUDI

Done at _____, on _____
LOCATION DATE Sachin JAIN

ASSIGNMENT

WHEREAS, WE,

1. **Debesh Kumar SAHU**, a citizen of India, having a mailing address located at 5775 Morehouse Drive, San Diego, California 92121 and a resident of Hyderabad, Andhra Pradesh, India,
2. **George CHERIAN**, a citizen of India, having a mailing address located at 5775 Morehouse Drive, San Diego, California 92121 and a resident of San Diego, California,
3. **Venkata Siva Prasad Rao GUDE**, a citizen of India, having a mailing address located at 5775 Morehouse Drive, San Diego California 92121 and a resident of San Diego, California,
4. **Neelakanta Venkata Seshachalam CHIMMAPUDI**, a citizen of India, having a mailing address located at 5775 Morehouse Drive, San Diego, California 92121 and a resident of San Diego, California,
5. **Sachin JAIN**, a citizen of India, having a mailing address located at 5775 Morehouse Drive, San Diego, California 92121 and a resident of Sunnyvale, California,

have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to **HIGH-SPEED DATA CHANNEL AVAILABILITY** (collectively the "INVENTIONS") for which WE have executed and/or may execute one or more patent applications therefor; and

WHEREAS, QUALCOMM Incorporated (hereinafter "ASSIGNEE"), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to said INVENTIONS, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, WE do hereby acknowledge that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, the entire right, title, and interest throughout the world in and to said INVENTIONS, including all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in the United States, including but not limited to U.S. Application No(s). **13/772,761** filed **February 21, 2013**, Qualcomm Reference No. **121184**, and all provisional applications relating thereto, together with U.S. Provisional Application No(s). **61/618,498**, filed **March 30, 2012**, Qualcomm Reference No. **121184P1**, (and do hereby authorize ASSIGNEE and its representative to hereafter add herein such application number(s) and/or filing date(s) when known), and all divisional applications, renewal applications, continuation applications, continuation-in-part

applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

AND WE further do acknowledge and agree that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;

AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND WE HEREBY represent that WE have full and exclusive, unencumbered right to sell, assign, convey and transfer all subject matter herein, and hereby covenant that WE have not and will not execute any writing or do any act whatsoever conflicting with these presents.

PATENT

QUALCOMM Ref. No. 121184

Page 3 of 3

Done at _____, on _____
LOCATION DATE

Debesh Kumar SAHU

Done at _____, on _____
LOCATION DATE

George CHERIAN

Done at _____, on _____
LOCATION DATE

Venkata Siva Prasad Rao GUDE

Done at _____, on _____
LOCATION DATE

Neelakanta Venkata Seshachalam CHIMMAPUDI

Done at SUNNY VALE, on 9/16/2014
LOCATION DATE


Sachin JAIN

PATENT

RECORDED: 10/09/2014

REEL: 033924 FRAME: 0478